

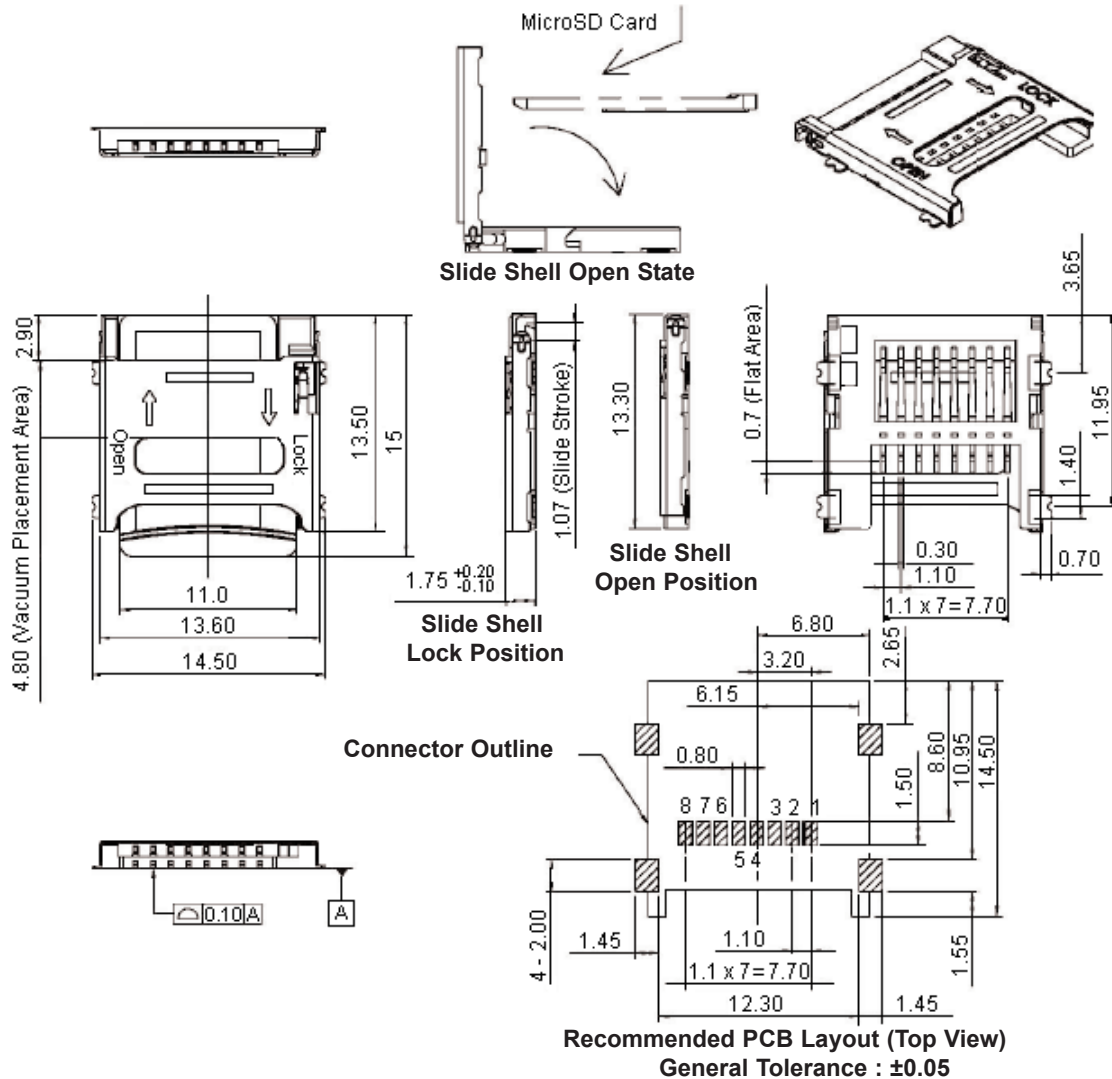


PART NO.

460DE08C3

REVISIONS

ECN #	REV	DESCRIPTION	DRAWN	DATE	CHECKD	DATE	APPRVD	DATE
-	A	RELEASED	Kiran	31/3/09	Veena	31/3/09	Farnell	14/04/09



Recommended PCB Layout (Top View)  
General Tolerance : ±0.05

Dimensions : Millimetres

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<b>DRAWN BY:</b>	<b>DATE:</b>
Kiran	31/03/09
<b>CHECKED BY:</b>	<b>DATE:</b>
Veena	31/03/09
<b>APPROVED BY:</b>	<b>DATE:</b>
Farnell	14/04/09

<b>DRAWING TITLE:</b>			
<b>Micro SD Connector - Hinged</b>			
<b>SIZE</b>	<b>DWG NO.</b>	<b>ELECTRONIC FILE</b>	<b>REV</b>
<b>A</b>	<b>M10002001</b>	<b>1686452-TDS_DWG</b>	<b>A</b>
<b>SCALE: NTS</b>		<b>U.O.M.: mm</b>	<b>SHEET: 1 OF 2</b>



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**Specifications:**

**Material**

Insulator : Liquid crystal polymer.  
 Contacts : Phosphor bronze.  
 Shell : Stainless steel (SUS301).

**Contact Plating**

Underplate : 50µ inches to 100µ inches nickel.  
 Contact area : 1µ inches gold.  
 Solder tails area : 1µ inches gold.

**Electrical**

Maximum rate voltage : 10V.  
 Maximum current rating : 0.5A.  
 Contact resistance : 80mΩ initial (final 100mΩ).  
 Minimum insulation resistance : 1000MΩ at 500V dc.  
 Dielectric withstanding voltage : 500V ac/minute.  
 Temperature range : -25°C to +85°C.  
 Mating cycles : 10,000 insertions.

**Pin Assignment Table**

Pin Number	Name
1	DAT2
2	CD/DAT3
3	CMD
4	VDD
5	CLK
6	VSS
7	DAT0
8	DAT1

**Part Number Table**

Description	Part Number
Connector, Micro SD, Hinged	460DE08C3

<http://www.farnell.com>  
<http://www.newark.com>  
<http://www.cpc.co.uk>

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<b>SCALE: NTS</b>		<b>U.O.M.: mm</b>	<b>SHEET: 2 OF 2</b>